



## SEMICONDUCTOR MANUFACTURING INTERNATIONAL CORPORATION

### 中芯國際集成電路製造有限公司\*

(Incorporated in the Cayman Islands with limited liability)

(於開曼群島註冊成立之有限公司)

(Stock Code: 981)

(股份代號: 981)

6 September 2023

Dear Shareholder(s),

#### **Semiconductor Manufacturing International Corporation (the "Company") 2023 Interim Report (the "Current Corporate Communication")**

We are pleased to inform you that the English and Chinese versions of the Company's Current Corporate Communication are now available on the Company's website at [www.smics.com](http://www.smics.com).

If you have any difficulty in receiving or gaining access to the Current Corporate Communication posted on the Company's website for any reason, we will upon your notice send the printed form of the Current Corporate Communication to you free of charge as soon as possible. Please also note that you are entitled at any time to change your choice of language and means of receipt of all future Corporate Communication<sup>(Note)</sup> by giving reasonable notice in writing to the Company's Hong Kong Share registrar, Computershare Hong Kong Investor Services Limited, by post (Address: 17M Floor, Hopewell Centre, 183 Queen's Road East, Wan Chai, Hong Kong) or by email (Email address: [smic.ecom@computershare.com.hk](mailto:smic.ecom@computershare.com.hk)).

If you have any queries about how to obtain a copy of the Current Corporate Communication or how to access the Current Corporate Communication on the Company's website, please call the hotline of the Company's Hong Kong Share registrar at (852) 2862 8688 during business hours from 9:00 a.m. to 6:00 p.m., Monday to Friday, excluding public holidays.

For and on behalf of  
**Semiconductor Manufacturing International Corporation**

*Note: Corporate Communication means any document issued or to be issued by an issuer for the information or action of holders of any of its securities, including but not limited to (a) the directors' report, its annual accounts together with a copy of the auditors' report and, where applicable, its summary financial report; (b) the interim report and, where applicable, summary interim report; (c) a notice of meeting; (d) a listing document; (e) a circular; and (f) a proxy form.*

\* For identification purposes only

敬啟者:

#### **中芯國際集成電路製造有限公司\* (「本公司」) 2023 年中期報告 (「本次公司通訊文件」)**

本公司欣然知會閣下本公司之本次公司通訊文件之中、英文版本現已登載於本公司網站 ([www.smics.com](http://www.smics.com))。

倘閣下因任何理由以致在收取或接收載於本公司網址上的本次公司通訊文件出現困難，本公司將於接到閣下通知後，盡快向閣下寄發本次公司通訊文件的印刷本，費用全免。閣下亦有權在任何時間以合理書面（地址為香港灣仔皇后大道東 183 號合和中心 17M 樓）或電郵（電郵地址為 [smic.ecom@computershare.com.hk](mailto:smic.ecom@computershare.com.hk)）方式通知本公司的港股份過戶登記處，香港中央證券登記有限公司，以更改今後所有公司通訊<sup>(附註)</sup>的語言版本及收取方式。

倘閣下對於如何索取本次公司通訊文件或如何在本公司網址上閱覽本次公司通訊文件有任何疑問，請致電本公司的港股份過戶登記處熱線 (852) 2862 8688，辦公時間為星期一至五（公眾假期除外）上午九時正至下午六時正。

中芯國際集成電路製造有限公司\*  
謹啟

二零二三年九月六日

附註：公司通訊即發行人已發出或將發出以供持有其證券的人士參照或採取行動的任何文件，其中包括（但不限於）：(a) 董事會報告、年度賬目連同核數師報告及（如適用）財務摘要報告；(b) 中期報告及（如適用）中期摘要報告；(c) 會議通知的函件；(d) 上市文件；(e) 股東通函；及(f) 代表委任表格。

\* 僅供識別

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